

Abstract:

Printed-circuit board and method for the precise assembly and soldering of electronic components on the surface of the printed-circuit board

The invention relates to a printed-circuit board (1) and a method for the precise assembly of electronic components on surface (12) of printed-circuit board (1), said electronic components being electrically and conductively attached to printed-circuit board (1) by means of a reflow soldering technique. For this purpose, a printed-circuit board (1) is used that has sections (2, 3) for receiving electronic components on its surface (12), said sections being at least partially adapted to the outside contour of respective electronic components. Said sections configured as slotted contours (3) or grooves (2) secure that the electronic components mounted after the application of solder paste are held in their desired positions prior to the actual soldering process.

In addition, the assembled printed-circuit board can be connected to a housing (1) composed of dome-type extensions (14) of an at least partly deformable material. Said extensions engage in cutouts (15, 16 or 17) provided in the printed-circuit board and pass through the latter, and a positive-linkage and/or frictional housing/printed-circuit board connection is established by deformation of said extensions (14). Further, an overvoltage protection plug for terminal blocks of the telecommunication technique with a voltage surge arrester (4) can be mounted that combines the two functions "earthing contact" and "fail-safe contact" in one part, and an assembly can be achieved with little expenses for assembly.

(Fig. 2)